

IN THE CLAIMS:

Please add the following claims:

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12. A processor for a spin coating device including a chuck defining a wafer plane, comprising:  
at least one dispenser; and  
a suction mechanism generally around said at least one dispenser and offset from said wafer plane.
13. The processor in claim 12, wherein said at least one dispenser further comprises:  
a first dispenser on a first side of said wafer plane; and  
a second dispenser on a second side of said wafer plane.
14. A bead remover for a wafer having an edge, comprising:  
a negative pressure mechanism configured to be spaced from said edge; and  
a solvent-dispensing mechanism aligned with said negative pressure mechanism.
15. The bead remover of claim 14, wherein said solvent-dispensing mechanism is concentric to said negative pressure mechanism.
16. The bead remover of claim 15, wherein said solvent-dispensing mechanism is generally within said negative pressure mechanism.
17. An edge bead remover configured to service a spinning wafer, comprising:  
a nozzle configured to apply a solvent to an edge of said wafer; and  
a vacuum mechanism enveloping said nozzle and offset from a surface of said wafer.
18. The edge bead remover of claim 17, wherein said vacuum mechanism is configured to remove said solvent from said edge.

19. The edge bead remover of claim 18, wherein said vacuum mechanism envelopes said edge.

20. A material removal system for a wafer having an edge, comprising:  
a negative pressure device defining a vacuum area intersecting said edge; and  
a solvent dispenser intersecting said vacuum area.

21. The material removal system of claim 20, wherein said negative pressure device is distal from said edge.

22. An edge bead removal system for a wafer having an edge and a top and a bottom, comprising:

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a first solvent nozzle poised above said top of said wafer at said edge;  
a second solvent nozzle poised below said bottom of said wafer at said edge; and  
a suction device encompassing said first solvent nozzle and said second solvent nozzle.

23. The edge bead removal system in claim 22, wherein said suction device encompasses said top and said bottom of said wafer at said edge.

24. A chemical dispensing system for a workpiece, comprising:

a negative pressure device defining a portal disposed toward and spaced from an edge of said workpiece; and  
a first solvent dispenser within said negative pressure device and disposed toward said edge.

25. The chemical dispensing system in claim 24, wherein said portal is spaced around said edge.

26. The chemical dispensing system in claim 25, further comprising a second solvent dispenser within said negative pressure device, disposed toward said edge, and opposing said first solvent dispenser.

27. The chemical dispensing system in claim 26, wherein said first solvent dispenser and said second solvent dispenser are within said portal.

28. A chemical remover for a substrate edge, comprising:

a nozzle directed toward said substrate edge and configured to couple to a solvent source; and

a vacuum device spaced from said substrate edge and directed toward said nozzle.

29. A profiler for a wafer edge, comprising:

AZ a solvent dispenser perpendicular to said wafer edge; and

a solvent vacuumer surrounding at least a portion of said solvent dispenser and separate from said wafer edge.

30. The profiler in claim 29, wherein said solvent dispenser further comprises a location wherein solvent exits said solvent dispenser; and wherein said solvent vacuumer surrounds said location.

31. The profiler in claim 30, further comprising an additional solvent dispenser perpendicular to said wafer edge; wherein said solvent vacuumer surrounds at least a portion of said additional solvent dispenser.

32. The profiler in claim 31, wherein said solvent dispenser is disposed toward a top side of said wafer edge.

33. The profiler in claim 32, wherein said additional solvent dispenser is disposed toward a bottom side of said wafer edge.

34. A device for an edge bead, comprising:

a dispenser configured to release a chemical toward said edge bead; and  
a splash controller around said dispenser, physically unattached from said edge bead, and configured to draw said chemical toward said splash controller.

35. The device in claim 34, wherein said splash controller is configured to generate a gas pressure around said edge bead that is lower than an ambient gas pressure.

36. The device in claim 35, wherein said splash controller is configured to physically intercept said chemical.

37. The device in claim 36, wherein said splash controller is around said edge bead.

38. A removal system for a workpiece having an overlying material, comprising:

a nozzle having an extended position and a retracted position, wherein said nozzle is disposed toward said workpiece and configured to dispense a chemical toward said workpiece while in said extended position; and

a suction applicator commensurately movable with said nozzle and defining a port around said nozzle, wherein said suction applicator is configured to withdraw said chemical and said material at a distance from said workpiece.

39. The removal system in claim 38, wherein said nozzle is further configured to dispense said chemical toward said material.

40. The removal system in claim 38, wherein said nozzle is further configured to dispense said chemical toward a portion of said workpiece interposed between said nozzle and said material.

41. A processor for a semiconductor wafer that is generally exposed to an ambient air pressure, comprising:

a splash control apparatus configured to define a lower air pressure area on more than one side of said workpiece; and  
at least one chemical dispenser poised toward said workpiece.

42. The processor in claim 41, wherein said splash control apparatus further comprises a housing overaccommodating a dimension of said workpiece.

43. The processor in claim 42, wherein said splash control apparatus defines an opening wider than a width of said workpiece.

Please cancel claims 1-33 and 38-40 without prejudice.